ARM, HP, SK Hynix join Hybrid Memory Cube group

Peter Clarke

7/4/2012 9:56 AM EDT

LONDON – ARM, Hewlett-Packard and SK Hynix have joined the Hybird Memory Cube Consortium (HMCC) led by Micron and Samsung, a sign of gathering momentum for this proposed application of 3-D memory stacks.

The three companies, which have technology expertise in processors, computers and memory, join Altera, IBM, Microsoft, Open-Silicon, Xilinx as well as Micron and Samsung working to draft an open interface specification for stacked memory.

One of the motivations for forming the HMCC is that the memory bandwidth required for next-generation high-performance computers and networking equipment has increased beyond what conventional memory architectures can provide. Breaking through the "memory wall" will require increased density and bandwidth at reduced power consumption, a goal of HMCC.

HMCC plans to deliver a final interface specification by the end of 2012.

"With the addition of ARM, HP and SK hynix as developers, who will help to determine the specific features, the consortium is well positioned to provide a new open standard for next-gen electronics," said Robert Feurle, Micron's vice president for DRAM marketing, in a statement.

Related links and articles:

www.hybridmemorycube.org

News articles:

Microsoft joins Micron memory cube effort

Micron broadening support for memory cube

IBM, Micron to build hybrid memory with TSVs

Micron, Samsung seek hybrid memory specification